

TC74AC299P, TC74AC299F, TC74AC299FW**8-BIT PIP SHIFT REGISTER WITH ASYNCHRONOUSCLEAR**

The TC74AC299 is an advanced high speed CMOS 8-BIT PIP SHIFT REGISTER fabricated with silicon gate and double-layer metal wiring C²MOS technology.

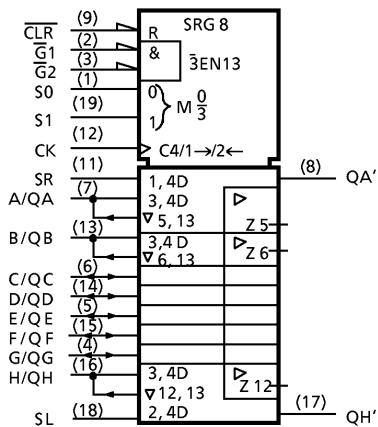
It achieves the high speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation.

It has a four modes (HOLD, SHIFT LEFT, SHIFT RIGHT and LOAD DATA) controlled by the two selection inputs (S0, S1).

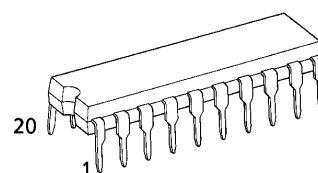
When one or both enable (\bar{G}_1 , \bar{G}_2) are high, the eight I/O outputs are forced to the high-impedance state; however, sequential operation or clearing of the register is not affected. All inputs are equipped with protection circuits against static discharge or transient excess voltage.

FEATURES:

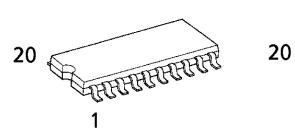
- High Speed..... $f_{MAX} = 150MHz$ (typ.) at $V_{CC} = 5V$
- Low Power Dissipation..... $I_{CC} = 8\mu A$ (Max.) at $T_a = 25^{\circ}C$
- High Noise Immunity..... $V_{NIH} = V_{NIL} = 28\%$ V_{CC} (Min.)
- Symmetrical Output Impedance... $|I_{OH}| = |I_{OL}| = 24mA$ (Min.) Capability of driving 50Ω transmission lines.
- Balanced Propagation Delays..... $t_{PLH} \approx t_{PHL}$
- Wide Operating Voltage Range.... V_{CC} (opr) = 2V ~ 5.5V
- Pin and Function Compatible with 74F299

IEC LOGIC SYMBOL

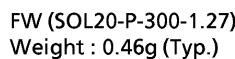
(Note) The JEDEC SOP (FW) is not available in Japan.



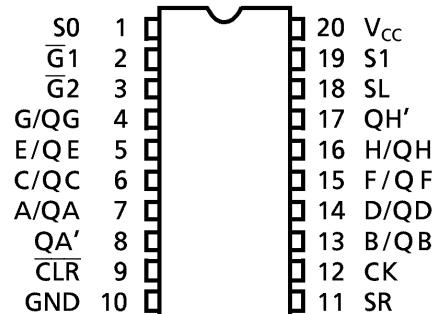
P (DIP20-P-300-2.54A)
Weight : 1.30g (Typ.)



F (SOP20-P-300-1.27)
Weight : 0.22g (Typ.)



FW (SOL20-P-300-1.27)
Weight : 0.46g (Typ.)

PIN ASSIGNMENT

(TOP VIEW)

APPLICATION NOTES

- 1) Do not apply a signal to any bus terminal when it is in the output mode. Damage may result.
- 2) All floating (high impedance) bus terminals must have their input levels fixed by means of pull up or pull down resistors.

TRUTH TABLE

MODE	INPUTS								INPUTS/OUTPUTS		OUTPUTS	
	CLR	FUNCTION SELECT		OUTPUT CONTROL		CK	SERIAL		A/QA	H/QH	QA'	QH'
		S1	S0	$\bar{G}1^*$	$\bar{G}2^*$		SL	SR				
CLEAR	L	H	H	X	X	X	X	X	Z	Z	L	L
	L	L	X	L	L	X	X	X	L	L	L	L
	L	X	L	L	L	X	X	X	L	L	L	L
HOLD	H	L	L	L	L	X	X	X	QA0	QH0	QA0	QH0
SHIFT RIGHT	H	L	H	L	L		X	H	H	QGn	H	QGn
SHIFT LEFT	H	H	L	L	L		X	L	L	QGn	L	QGn
LOAD	H	H	H	X	X		X	X	a	h	a	h

* When one or both output controls are high, the eight input/output terminals are in the high-impedance state; however sequential or clearing of the register is not affected.

Z : High Impedance

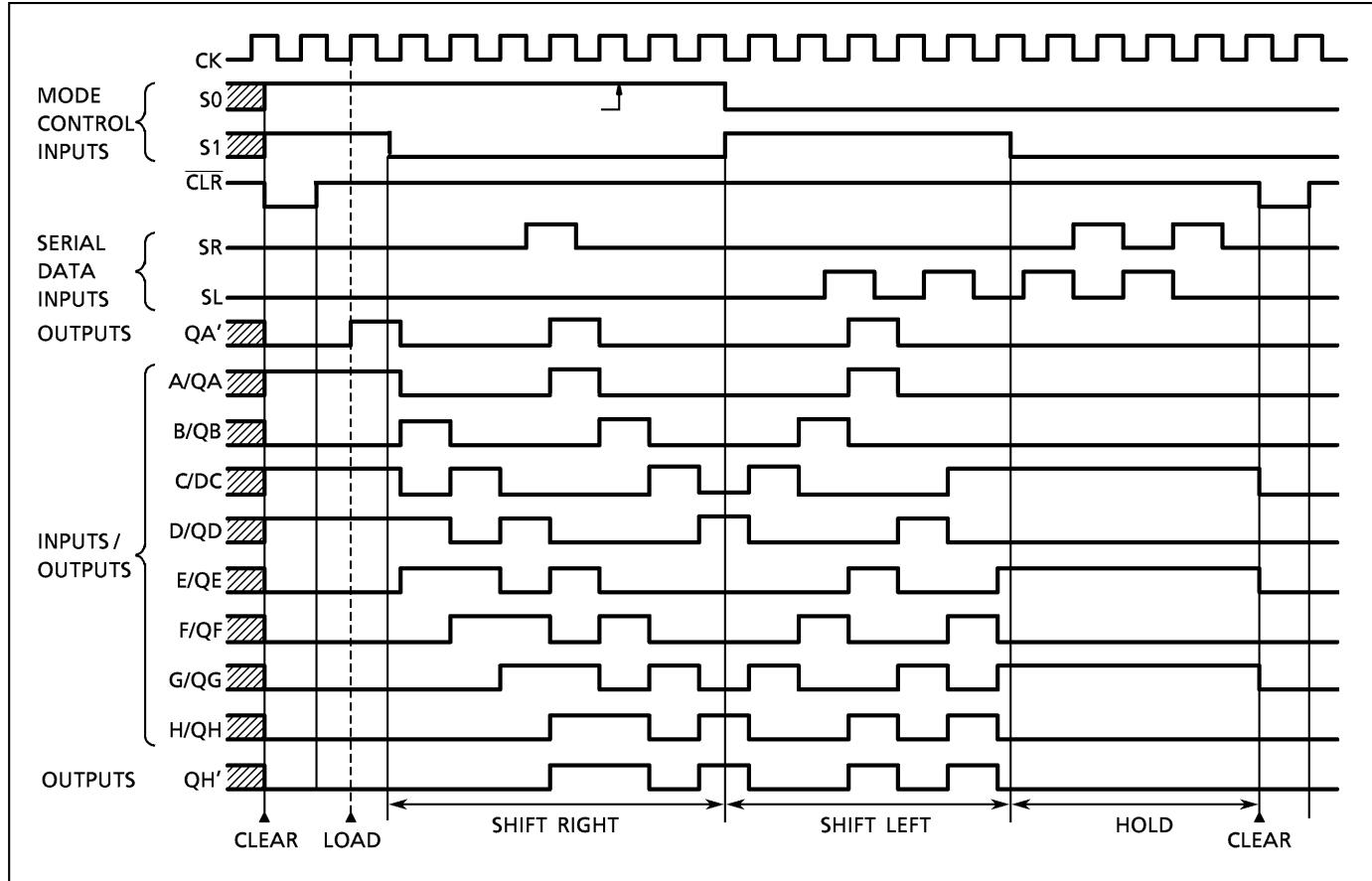
Qn0 : The level of Qn before the indicated steady-state input conditions were established.

Qnn : The level of Qn before the most recent active transition indicated by or .

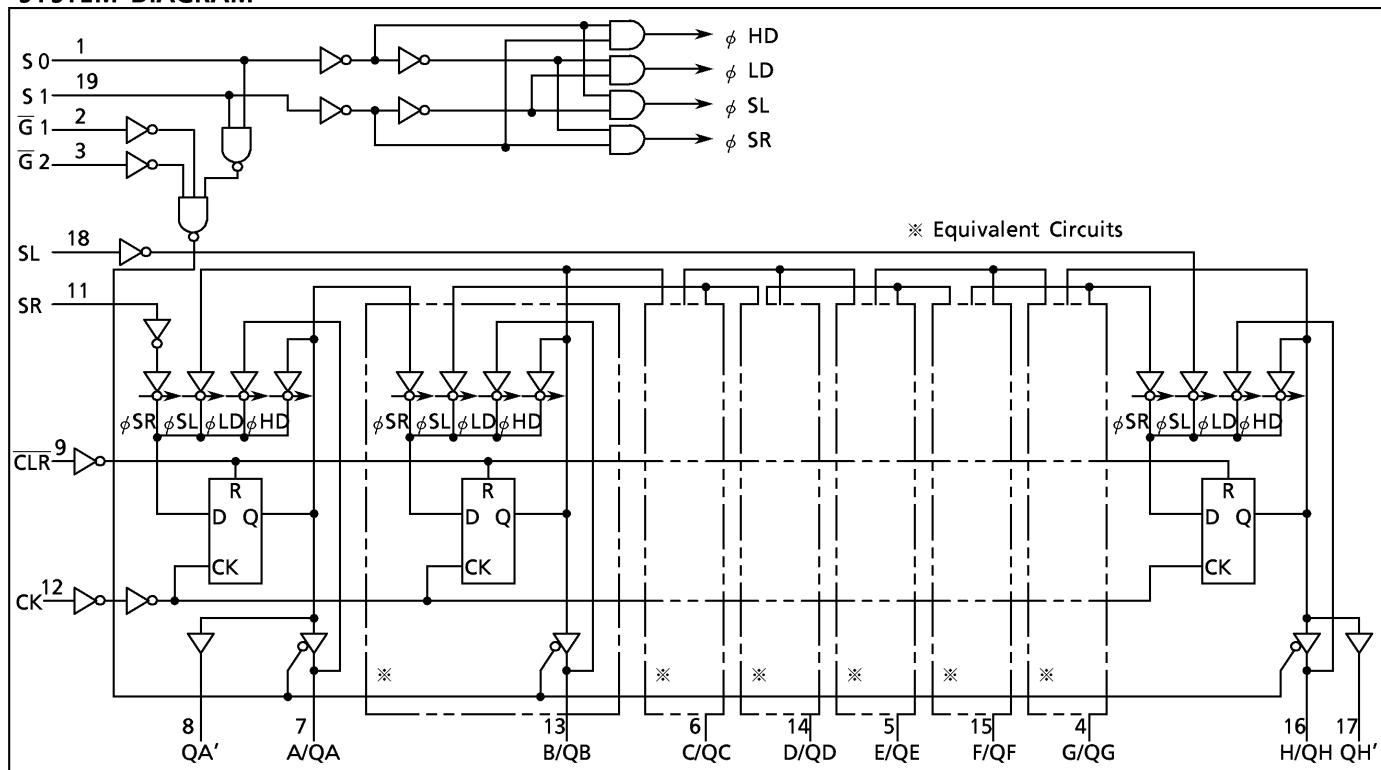
a, h : The level of the steady-state inputs A, H, respectively.

X : Don't Care.

TIMING CHART



SYSTEM DIAGRAM



ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage Range	V_{CC}	-0.5~7.0	V
DC Input Voltage	V_{IN}	-0.5~ $V_{CC} + 0.5$	V
DC Output Voltage	V_{OUT}	-0.5~ $V_{CC} + 0.5$	V
Input Diode Current	I_{IK}	± 20	mA
Output Diode Current	I_{OK}	± 50	mA
DC Output Current	I_{OUT}	± 50	mA
DC V_{CC} /Ground Current	I_{CC}	± 250	mA
Power Dissipation	P_D	500 (DIP)* / 180 (SOP)	mW
Storage Temperature	T_{stg}	-65~150	°C

*500mW in the range of $T_a = -40^{\circ}\text{C} \sim 65^{\circ}\text{C}$. From $T_a = 65^{\circ}\text{C}$ to 85°C a derating factor of $-10\text{mW}/^{\circ}\text{C}$ should be applied up to 300mW.

RECOMMENDED OPERATING CONDITIONS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage	V_{CC}	2.0~5.5	V
Input Voltage	V_{IN}	0~ V_{CC}	V
Output Voltage	V_{OUT}	0~ V_{CC}	V
Operating Temperature	T_{opr}	-40~85	°C
Input Rise and Fall Time	dt/dV	0~ 100 ($V_{CC} = 3.3 \pm 0.3\text{V}$) 0~ 20 ($V_{CC} = 5 \pm 0.5\text{V}$)	ns/V

DC ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION	V_{CC} (V)	Ta = 25°C			Ta = -40~85°C		UNIT
				MIN.	TYP.	MAX.	MIN.	MAX.	
High - Level Input Voltage	V_{IH}		2.0 3.0 5.5	1.50 2.10 3.85	— — —	— — —	1.50 2.10 3.85	— — —	V
Low - Level Input Voltage	V_{IL}		2.0 3.0 5.5	— — —	— — —	0.50 0.90 1.65	— — —	0.50 0.90 1.65	V
High - Level Output Voltage	V_{OH}	$V_{IN} = V_{IH}$ or V_{IL}	$I_{OH} = -50\mu A$	2.0 3.0 4.5	1.9 2.9 4.4	2.0 3.0 4.5	— — —	1.9 2.9 4.4	V
			$I_{OH} = -4mA$ $I_{OH} = -24mA$ $I_{OH} = -75mA^*$	3.0 4.5 5.5	2.58 3.94 —	— — —	— — —	2.48 3.80 3.85	
			$I_{OL} = 50\mu A$	2.0 3.0 4.5	— — —	0.0 0.0 0.0	0.1 0.1 0.1	— — —	
Low - Level Output Voltage	V_{OL}	$V_{IN} = V_{IH}$ or V_{IL}	$I_{OL} = 12mA$ $I_{OL} = 24mA$ $I_{OL} = 75mA^*$	3.0 4.5 5.5	— — —	— 0.36 0.36	— — —	0.44 0.44 1.65	V
3 - State Output Off - State Current	I_{OZ}	$V_{IN} = V_{IH}$ or V_{IL} $V_{OUT} = V_{CC}$ or GND	5.5	—	—	± 0.5	—	± 5.0	
Input Leakage Current	I_{IN}	$V_{IN} = V_{CC}$ or GND	5.5	—	—	± 0.1	—	± 1.0	
Quiescent Supply Current	I_{CC}	$V_{IN} = V_{CC}$ or GND	5.5	—	—	8.0	—	80.0	μA

* : This spec indicates the capability of driving 50Ω transmission lines.

One output should be tested at a time for a 10ms maximum duration.

TIMING RECOMMENDED OPERATING CONDITIONS (Input $t_r = t_f = 3ns$)

PARAMETER	SYMBOL	TEST CONDITION	Ta = 25°C		Ta = -40~85°C		UNIT
			V_{CC} (V)	LIMIT	LIMIT	LIMIT	
Minimum Pulse Width (CK)	$t_W(L)$ $t_W(H)$		3.3 ± 0.3 5.0 ± 0.5	8.0 5.0	8.0 5.0	8.0 5.0	ns
Minimum Pulse Width (CLR)	$t_W(L)$		3.3 ± 0.3 5.0 ± 0.5	7.0 5.0	7.0 5.0	7.0 5.0	
Minimum Set - up Time (SL, SR, A~H)	t_s		3.3 ± 0.3 5.0 ± 0.5	6.0 4.0	6.0 4.0	6.0 4.0	
Minimum Set - up Time (S0, S1)	t_s		3.3 ± 0.3 5.0 ± 0.5	11.9 7.0	13.6 7.0	13.6 7.0	
Minimum Hold Time (SL, SR, A~H)	t_h		3.3 ± 0.3 5.0 ± 0.5	1.0 1.0	1.0 1.0	1.0 1.0	
Minimum Hold Time (S0, S1)	t_h		3.3 ± 0.3 5.0 ± 0.5	0.0 0.0	0.0 0.0	0.0 0.0	
Minimum Removal Time (CLR)	t_{rem}		3.3 ± 0.3 5.0 ± 0.5	5.0 3.0	5.0 3.0	5.0 3.0	

AC ELECTRICAL CHARACTERISTICS ($C_L = 50\text{pF}$, $R_L = 500\Omega$, $t_r = t_f = 3\text{ns}$)

PARAMETER	SYMBOL	TEST CONDITION	Ta = 25°C			Ta = -40~85°C		UNIT
			V _{CC} (V)	MIN.	TYP.	MAX.	MIN.	
Propagation Delay Time (CK-QA', QH')	t_{pLH} t_{pHL}		3.3 ± 0.3 5.0 ± 0.5	—	10.6 6.8	18.4 10.5	1.0 1.0	21.0 12.0
Propagation Delay Time (CLR-QA', QH')	t_{pLH} t_{pHL}		3.3 ± 0.3 5.0 ± 0.5	—	8.1 6.1	14.0 9.2	1.0 1.0	16.0 10.5
Propagation Delay Time (CK-QA ~ QH)	t_{pLH} t_{pHL}		3.3 ± 0.3 5.0 ± 0.5	—	10.9 7.3	19.3 10.5	1.0 1.0	22.0 12.0
Propagation Delay Time (CLR-QA ~ QH)	t_{pLH} t_{pHL}		3.3 ± 0.3 5.0 ± 0.5	—	9.8 6.7	16.7 10.9	1.0 1.0	19.0 12.4
Output Enable Time	t_{pZL} t_{pZH}		3.3 ± 0.3 5.0 ± 0.5	—	9.9 6.6	17.5 9.6	1.0 1.0	20.0 11.0
Output Disable Time	t_{pLZ} t_{pHZ}		3.3 ± 0.3 5.0 ± 0.5	—	8.1 6.4	14.0 9.6	1.0 1.0	16.0 11.0
Maximum Clock Frequency	f _{MAX}		3.3 ± 0.3 5.0 ± 0.5	45 80	90 140	—	45 80	—
Input Capacitance	C _{IN}			—	5	10	—	10
Bus Input Capacitance	C _{I/O}			—	13	—	—	—
Power Dissipation Capacitance	C _{PD} (1)			—	137	—	—	—

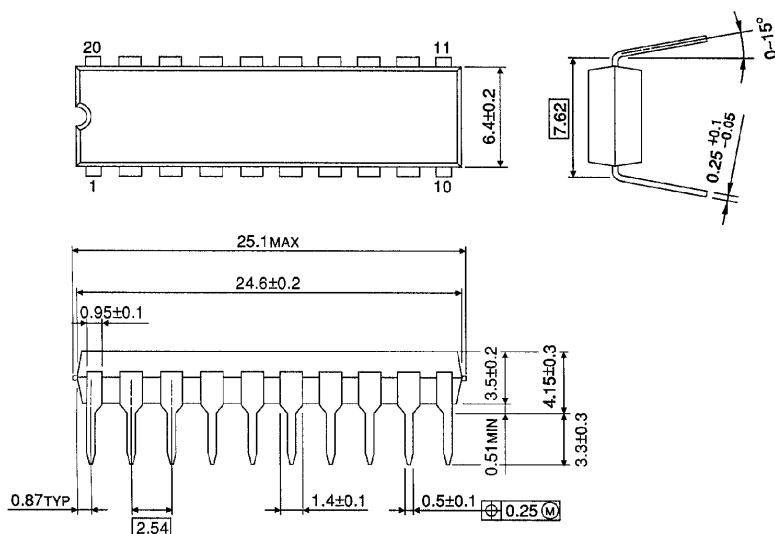
Note(1) C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

Average operating current can be obtained by the equation:

$$I_{CC(\text{opr})} = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC}$$

DIP 20PIN PACKAGE DIMENSIONS (DIP20-P-300-2.54A)

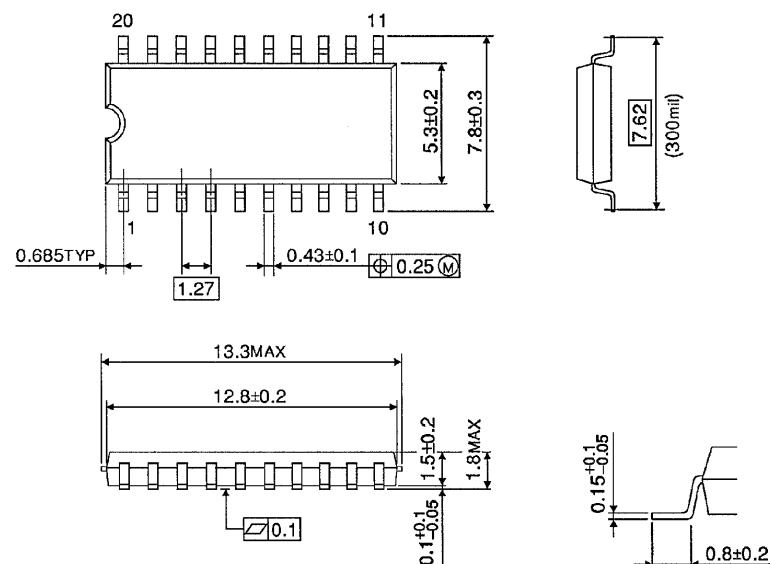
Unit in mm



Weight : 1.30g (Typ.)

SOP 20PIN (200mil BODY) PACKAGE DIMENSIONS (SOP20-P-300-1.27)

Unit in mm

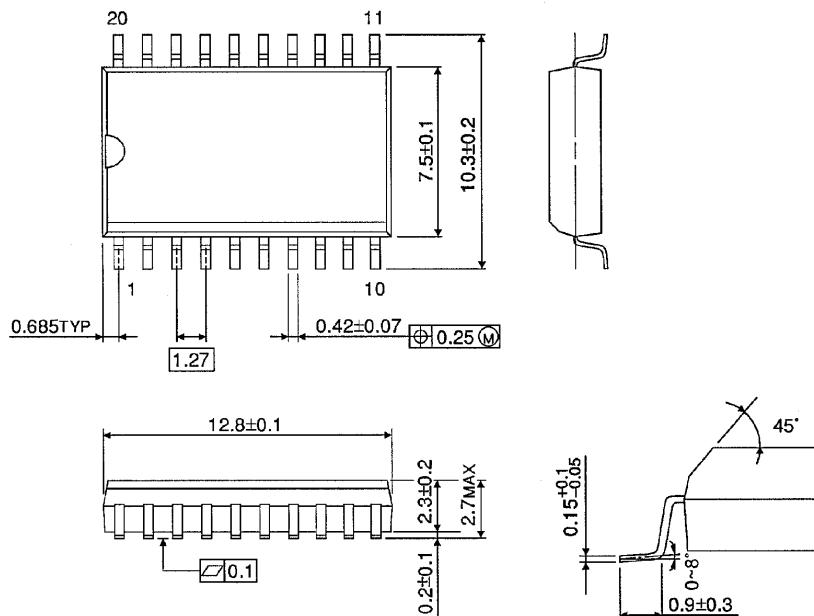


Weight : 0.22g (Typ.)

SOP 20PIN (300mil BODY) PACKAGE DIMENSIONS (SOL20-P-300-1.27)

Unit in mm

(Note) This package is not available in Japan.



Weight : 0.46g (Typ.)

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